

Title (en)
Soldering procedure.

Title (de)
Lötverfahren.

Title (fr)
Procédé de brasage tendre.

Publication
EP 0524331 B1 19940706 (DE)

Application
EP 91112280 A 19910722

Priority
EP 91112280 A 19910722

Abstract (en)
[origin: EP0524331A1] For a contact soldering procedure by means of soldering paste, it is proposed to carry a separating foil (4) between soldering electrode (5) and soldering paste (3) in order to prevent direct contact between the soldering electrode (5) and the soldering paste (3) and to consequently prevent contamination of the soldering electrode (5). <IMAGE>

IPC 1-7
B23K 1/00; **B23K 3/047**

IPC 8 full level
B23K 3/08 (2006.01); **B23K 35/14** (2006.01); **H05K 3/34** (2006.01)

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